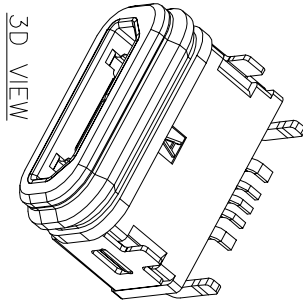
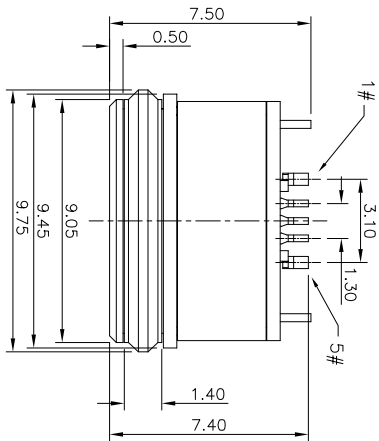
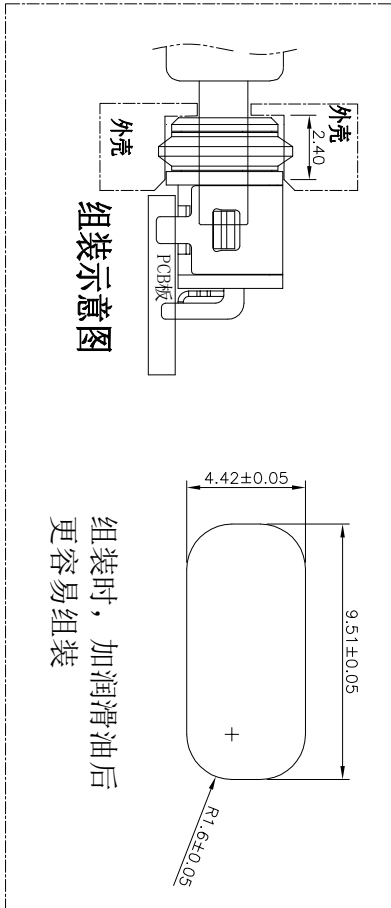


REV.		ECN NO.		LOCATION		REVISIONS		DESCRIPTION		DATE		DESIGN	
X1		NA							INITIAL RELEASE		2017.09.25	WIND	

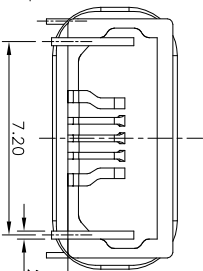
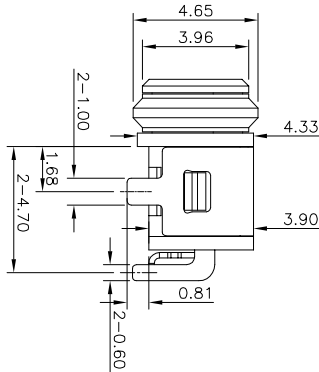
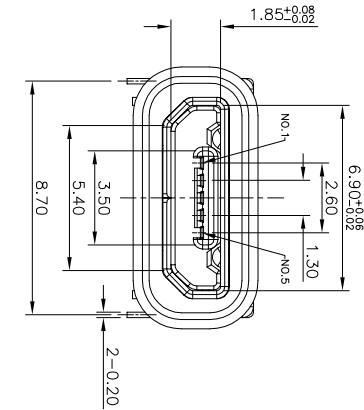


3D VIEW



组装示意图

组装时，加润滑油后
更容易组装

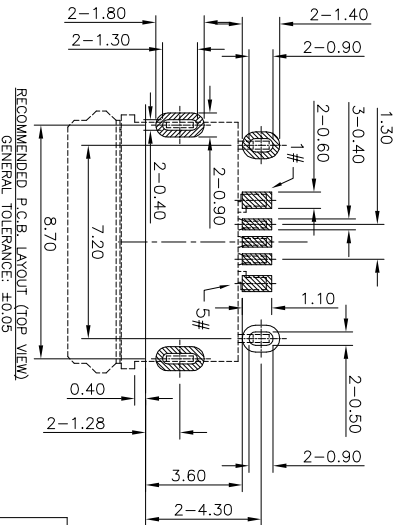
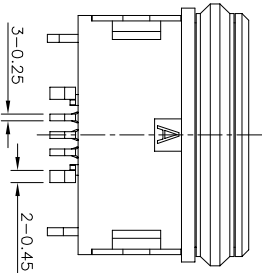


ALL SOLDER TAILS

⑦	Oval ring	1	Rubber	Block	
⑥	Glue	1	-----	Block	
⑤	U-shaped frame	1	Copper alloy or stainless	Nickel plated	
④	Inner shell	1	Copper alloy or stainless	Nickel plated	
③	Terminal	5	Copper alloy, 0.1st	Solder plated on Gold Area.	
②	Outer shell	1	High temperature thermoplastic	Block	
①	Body	1	High temperature thermoplastic	Block	
NO.	DESCRIPTION	QTY	MATERIAL	REMARK	

SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:
 - 1.1. RATING: 3A(PIN1&5),0.5A(PIN2&3&4);
 - 1.2. CONTACT RESISTANCE: 50 mΩ MAX.(INITIAL);
 - 1.3. DIELECTRIC WITHSTANDING: 500V AC MIN.;
 - 1.4. INSULATION RESISTANCE: 1000MΩ MIN.;
2. DURABILITY: 10,000 CYCLES MIN.;
3. INSERTION FORCE: 3.5Kgf (35N) Max.;
4. EXTRACTION FORCE: 0.8kgf (8N) Min.;
5. WATER PROOFNESS:THIS PRODUCT IS BASED ON IPX8(1.5m,30min)
6. PLUG INTERFACE DIMENSIONS CONFORM TO USB2.0 SPEC.
7. PACKAGING: TAPE & REEL.



RECOMMENDED P.C.B. LAYOUT (TOP VIEW)
GENERAL TOLERANCE: ±0.05

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the property of E-Zone
development corporation.

深圳市合众益华科技有限公司

Contact Number	Signal Name	Remarks
1#	VBUS	Power
2#	D-	Date-
3#	D+	Date+
4#	ID	Reserve or Gound
5#	GND	Gound